

S29PL032J

CS 81187

Qualification of: S29PL032J, 32 Megabit 3.0 Volt-only, Simultaneous-Read/Write Flash Memory with Enhanced VersatileIO™ Control in VBK048 (8.15 x 6.15 x 1.0mm) 48 Ball, Very Thin Fine Pitch Ball Grid Array Package (FBGA)



Reliability Qualification Summary

CONFIDENTIAL

NOTICE: The material in this report is confidential. It is prepared to assist in the qualification of our product. It is declassified for the internal use of our customers only, and may be modified to meet the needs of specific customers. It also serves as a record of full qualification according to JESD47 and AEC-Q100 Grade 1 requirements.

Additionally, the package details (material set, assembly location, etc.) are specific to the qual vehicle used for the qualification. Alternate material sets and assembly locations may be qualified for the product. Production material can be assembled with any qualified material set and at any qualified assembly location. Tests are performed in accordance with AEC-Q100 and relevant JEDEC specifications.

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I. Product Information

Product Description: S29PL032J

32 Megabit 3.0 Volt-only, Simultaneous-Read/Write Flash Memory with Enhanced VersatileIO™ Control

Package: VBK048

Qualification: 81187

Description: (8.15 x 6.15 x 1.0mm) 48 Ball, Very Thin Fine Pitch Ball Grid Array Package (FBGA)

Theta Ja: 39 °C/W

Psi Jt: 11 °C/W

Assembly Location: Spansion Thailand

Molding Compound: RoHS Compliant Epoxy Resin

Substrate/Leadframe: BT Resin Substrate

Die Attachment: Paste

Lead Finish: 96.5Sn3.0Ag0.5Cu Spheres

Bond Wire: Gold

Comments:

Est. Field Temperature: 55 °C

Life Test Temperature: 150 °C

Est. DC Field Current: 21 mA

Life Test Dynamic Current: 4 mA

Est. Field Voltage: 3.0 V

Life Test Voltage: 3.6 V

Est. Field Power Dissipation: 63 mWatts

Est. Stress Power Dissipation: 14.4 mWatts

Est. Field Tj: 57.4 °C

Est. Stress Tj: 150.5 °C

Die: 98M53B

Die Size: 4.53 x 3.86 mm

Process: CS69S (110nm)

Fab: Spansion Takaku

Type: Floating Gate

Density: 32M

II. CS69S/LS Life Test Failure Rate Calculation

HTOL Stress Temperature - 150 °C

Failure Mechanism	Read Points / Test Results				Modeling Parameters @ 55°C					Avg. Failure Rate FITS @ 55°C, 60% Conf.	
	24 hrs	168 hrs	1000 hrs	2000 hrs	Ea eV	TAF	VAF	OAF	MTTF (yrs)	Early Life	Inherent Life
PLASTIC											
Sample Size	13605	13089	960	120							
Zero fails, Process ave. Ea	0 *	0	0	0	0.66	135	1	135		17	3
Totals	0	0	0	0					38052	17	3

* Contributes to early life FITS

Data Retention Bake - 150 °C

Reliability Stress	Number of Rejects	Sample Size	Failure Rate %	Failure Mechanism
500 hrs	0	6667	0.00	No Failures
1000 hrs	0	7566	0.00	No Failures
2000 hrs	0	7249	0.00	No Failures

III. Summary of Stress Test Results

Stress Test	Stress Condition	Package Type	Sample Size	Num. of Lots	Num. of Fails	Failure Rate %	Comments
Data From Qualification 81187:							
HTOL (EL)	(3.6V, 150°C)	VBK048 ¹	77	1	0	0.00	168 hours
ESD CDM	N/A	VBK048 ¹	15	1	Passed	1.0kV	
ESD HBM	(100pF, 1500 Ohms)	VBK048 ¹	60	1	Passed	2.0kV	
Latch Up	(125°C, +/- 100mA)	VBK048 ¹	12	1	Passed		
Endurance (10k)	(90°C, 3.6V)	VBK048 ¹	64	1	0	0.00	10k cycles
Generic Reference Data:							
Preconditioning	(PC2/260°C, +0°C/-5°C)	VDC048 ²	498	3	Passed	Jedec L3	
Precon+Temp Cycle	(PC2/260°C, -40°C/150°C)	VDC048 ²	249	3	0	0.00	1000 cycles
Precon+HAST	(PC2/260°C, Biased, 110°C/85% RH)	VDC048 ²	249	3	0	0.00	264 hours
Steam Pressure Pot	(121°C/100%RH/15PSIG)	VDC048 ²	249	3	0	0.00	168 hours

Notes / Justification: 1) Results from Qual 81187, S29PL032J, 32M CS69S (110nm) Floating Gate in 48 Ball vFBGA (8.15 x 6.15 x 1mm)
 2) Results from Qual 4982, S29NS128J in 48 Ball vFBGA (9.95 x 10.95 x 1mm) - Same Fab and Flash Technology, Similar Package

Preconditioning Flows: PC2 (JEDEC L3): Bake 125°C, 24hr => Soak @ 30°C/60%RH, 192hr => 3x Reflow

IV. Revision History

Section	Description
Revision A - 1/4/2007	Initial Release.

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